Special Issue

Multimodal Affective Computing

Message from the Guest Editors

This Special Issue welcomes original research papers concerned with both theoretical and applied aspects of multimodal affective computing. Review articles describing the current state-of-the-art of multimodal affective computing are highly encouraged, including overviews of data and computational resources available. All submissions to this Special Issue must include substantial aspects from affective computing and multimodality. Possible topics include but are not limited to the following:

- Machine learning algorithms for multimodal affective computing;
- Theoretical aspects of multimodal affective computing models;
- Combination and fusion of modalities for affective computing;
- Robustness of multimodal affective computing methods in the wild;
- Multimodal affective computing on the edge for IoT devices;
- Data and method resources for multimodal affective computing;

User profiling and adaptation methods for multimodal affective computing

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Deadline for manuscript submissions

closed (31 March 2021)

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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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